

**In the Specification**

At page 12, lines 8 – 13, please replace the paragraph as follows (underlined denotes replacements additions and strikethrough notes deletions):

As discussed above, the present invention is applicable to a variety of integrated circuit dies. In this regard, and for more information generally regarding integrated circuit analysis and specifically regarding the [[us]]use of liquid crystal in the analysis of integrated circuit dies, reference may be made to U.S. Patent Application Serial No. 09/520,597, now US Patent No. 6,488,405 (~~AMDA.439PA/TT3683~~) entitled “Flip Chip Defect Analysis Using Liquid Crystal” and filed on March 8, 2000, which is fully incorporated herein by reference.